

ABSTRACT

In a method of manufacturing an electronic device, a first side edge of a first substantially planar panel including a display is hingedly coupled to a second substantially planar panel selected from a first set of panels. The second panel includes a first interface. A second side edge of the first panel is hingedly coupled to a third substantially planar panel selected from a second set of panels. The third panel includes a second interface. A kit to assemble an electronic device comprises three substantially planar panels. A first panel includes a display. A second panel includes a first interface and is configured to be hingedly coupled to a first side edge of the first panel. A third panel includes a second interface and is configured to be hingedly coupled to a second side edge of the first panel.